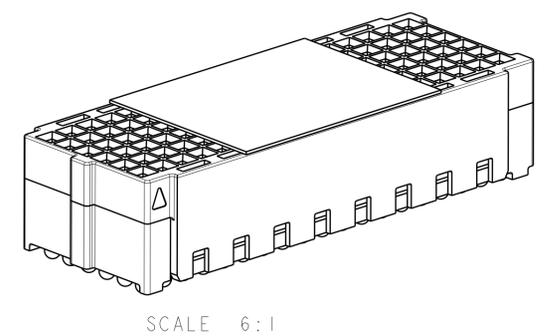
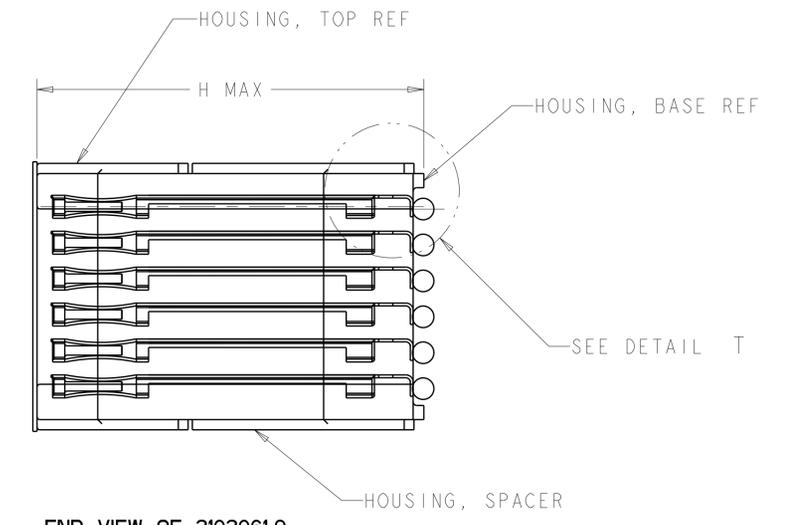
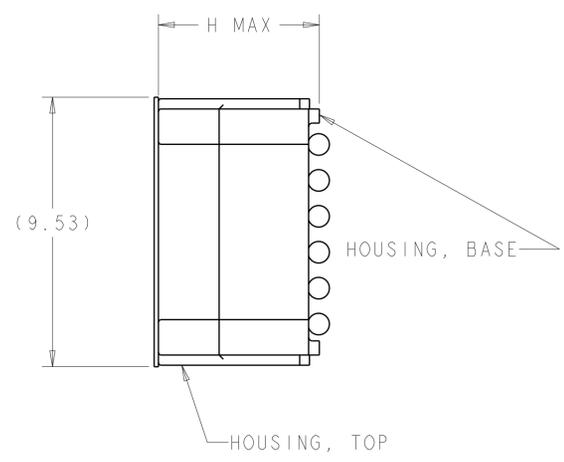
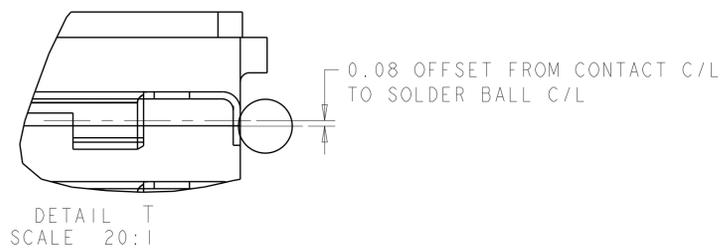
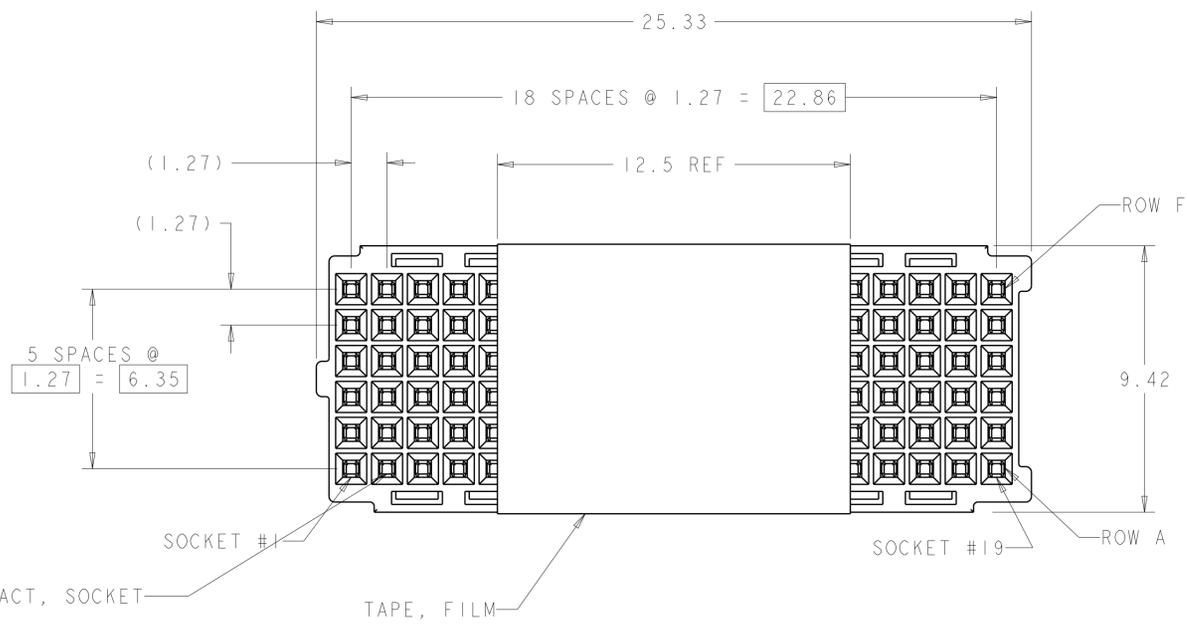
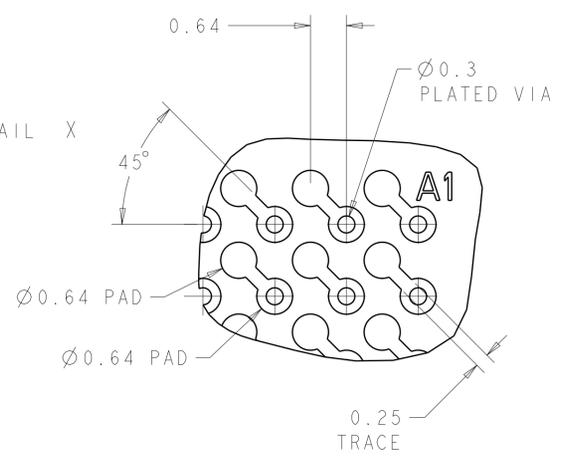
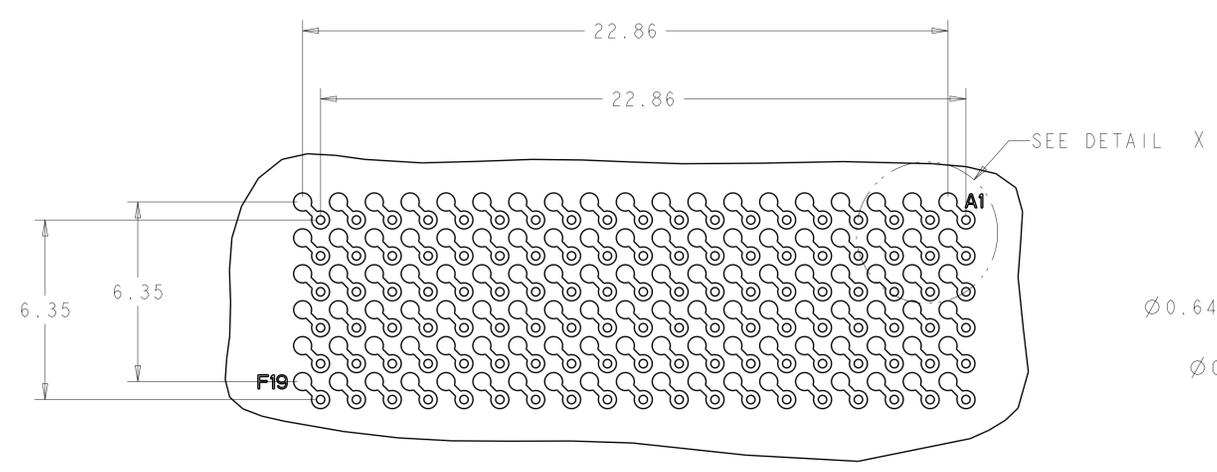
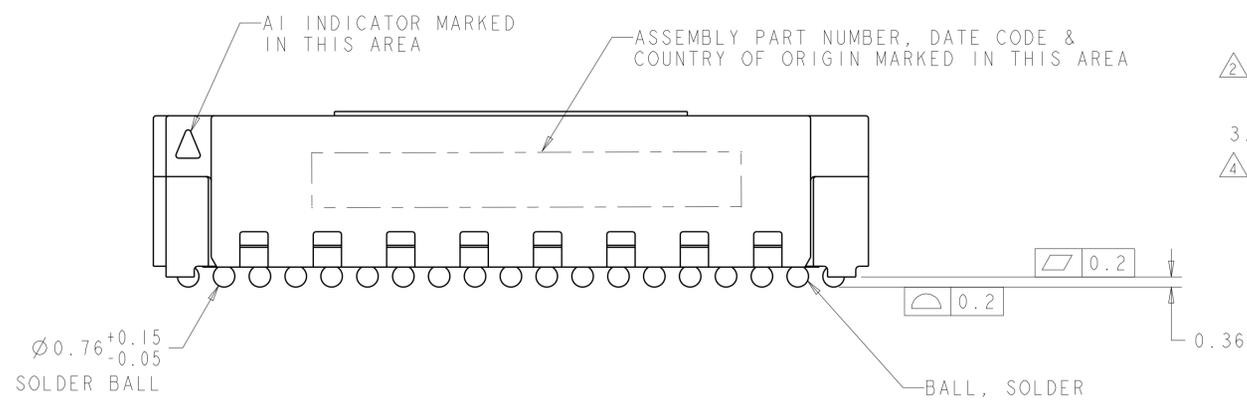


REVISIONS					
P.	LTN	DESCRIPTION	DATE	DMN	APVD
J		REV PER ECO 18-010457	7-24-18	CT	CJ



- ⚠ MATERIAL: HOUSINGS; LCP, COLOR-NATURAL CONTACT; BERYLLIUM COPPER SOLDER BALL; SEE TABLE TAPE, FILM; KAPTON WITH SILICON ADHESIVE
- ⚠ FINISH: CONTACT; GOLD (SEE TABLE) ON MATING AREA OVER NICKEL ON ENTIRE CONTACT.
- 3. PRODUCT IS PACKAGED ON TAPE AND REELED.
- ⚠ PRELIMINARY PART



⚠	2102060-2	17	1.27 μm	13	LEAD FREE PER SAC405	1-2102061-8
⚠	2102060-1	17	1.27 μm	13	TIN LEAD	1-2102061-7
	2102060-4	15	0.76 μm	11	LEAD FREE PER SAC405	1-2102061-6
	2102060-3	15	0.76 μm	11	TIN LEAD	1-2102061-5
	2102060-2	15	1.27 μm	11	LEAD FREE PER SAC405	1-2102061-4
	2102060-1	15	1.27 μm	11	TIN LEAD	1-2102061-3
	2102060-4	8	0.76 μm	14	LEAD FREE PER SAC405	1-2102061-2
	2102060-3	18	0.76 μm	14	TIN LEAD	1-2102061-1
	2102060-2	18	1.27 μm	14	LEAD FREE PER SAC405	1-2102061-0
	2102060-1	18	1.27 μm	14	TIN LEAD	2102061-9
	2102060-4	12	0.76 μm	8	LEAD FREE PER SAC405	2102061-8
	2102060-3	12	0.76 μm	8	TIN LEAD	2102061-7
	2102060-4	10	0.76 μm	6	LEAD FREE PER SAC405	2102061-6
	2102060-3	10	0.76 μm	6	TIN LEAD	2102061-5
	2102060-2	12	1.27 μm	8	LEAD FREE PER SAC405	2102061-4
	2102060-1	12	1.27 μm	8	TIN LEAD	2102061-3
	2102060-2	10	1.27 μm	6	LEAD FREE PER SAC405	2102061-2
	2102060-1	10	1.27 μm	6	TIN LEAD	2102061-1
	MATING PART NUMBER	MATED STACK HEIGHT (mm)	GOLD PLATING THICKNESS	H MAX REF	SOLDER BALL MATERIAL	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT. DWN LG DOWTY 23JUL2009. CHK K DOWHOWER 23JUL2009. APVD K DOWHOWER 23JUL2009.

TE Connectivity

ASSEMBLY, SOCKET, 114 POSITION, MEZALOK STACKING CONNECTOR

SIZE CAGE CODE DRAWING NO. RESTRICTED TO A100779C=2102061

CUSTOMER DRAWING SCALE 8:1 SHEET 1 OF 1 REV J